



## ARBITAL Solutions

### Product Data Sheet : ARSOL 230 Flux

#### DESCRIPTION

ARSOL 230 is a Halide Free No clean flux, with fine wetting properties, used for both Pb free and Sn/Pb soldering applications.

#### FEATURES AND BENEFITS

- Complies with Halide free standards, which is environment friendly.
- Fine soldering in both single and dual wave soldering process.
- High temperature stability, less surface tension and high through hole penetration rate.
- Good cosmetics, no need to clean. Non-hygroscopic, Tack-free and non-corrosive residues.
- ARSOL-230 is suitable for use on the following metal surface, provided the surfaces are not heavily tarnished. Cadmium, OSP, Tin, Copper, Gold, Zinc and Silver.

#### APPLICATIONS

Can be applied by Foam, spray, Dipping and brushing application. Uniform coating of flux is required on the board to achieve good results. To meet electrical stability and consistent soldering performance, materials used shall comply with Ionic cleanliness.

OPERATING PARAMETER	
Amount of Flux Applied	1,200 – 2,000 µg/in <sup>2</sup> solids
Top-Side Preheat Temperature	85 - 120°C
Bottom side Preheat Temperature	100 - 140°C
Maximum Ramp Rate of Topside Temperature (to avoid component damage)	3°C/second (35°F/second) maximum
Contact Time in the Solder (includes Chip Wave and Primary Wave)	3 – 6 seconds
Wave contact angle	4° ~ 6°
Solder Pot Temperature:	245-255°C for 63/37, 255-265°C for Lead Free SAC alloys.

These are general guidelines which have proven to yield excellent results; however, depending upon your equipment, components, and circuit boards, your optimal settings may be different. In order to optimize your process, it is recommended to perform a design experiment, optimizing the most important variables (amount of flux applied, conveyor speed, topside preheat temperature, solder pot temperature and board orientation).

## PHYSICAL AND CHEMICAL PROPERTIES

Appearance:	Clear, light amber (Pale Yellow) color
Acid number mg KOH/g:	18.5 +/- 1
IPC-J-STD-0004 Designation:	ROLO
Flash point:	18°C
Solids Content, wt/wt	4.0%
Ph (5% aqueous solution)	3.3+/- 0.2
Specific gravity @ 25°C:	0.794 +/- 0.02 (Can maintain the specific gravity using IPA Ultra Pure in foam and dip soldering application).
Reliability:	Meets IPC, JIS for corrosion and copper mirror tests, Bellcore Surface Insulation Resistance and Electro migration requirements.
Shelf Life :	18 months
IPC J-STD-004A Comb - UP and Down un-cleaned	Pass

### RESIDUE REMOVAL:

**ARSOL-230** Flux is a no-clean, flux residues are designed to be left on the board.

If desired, Flux residues can be removed with water Based cleaner AS Aqua Clean-7, Solvent based cleaners Biosol G-10, Biosol G-25 cleaner or EG grade IPA.

### TOUCH-UP/REWORK:

**ARSOL-220** is recommended for hand soldering applications.

## PACKAGING

Packaging is available in 5 and 20 Litres.

## HEALTH AND SAFETY

Observe standard precautions for handling. Eye and skin protection must be provided. Avoid breathing of liquid.

Use in well ventilated areas, DO NOT SMOKE, use of solvent resistant gloves.

Flammable, keep away from sparks and open flames.

Remove skin splashes by immediate washing with soap and water.

For detailed information refer to the Safety Data Sheet (MSDS) available on request.

Contact: Arbutal Solutions Private Limited, 12, SIDCO Industrial Estate, Gummidipoondi, Thiruvallur Dt. India.

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